

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	OPTIMUM PADSET FOR WIRE BONDING RF TECHNOLOGIES WITH HIGH-Q INDUCTORS						
<p>Application Number :</p> <p>Confirmation Number:</p> <p>First Named Applicant: Douglas Coolbaugh</p> <p>Attorney Docket Number: BUR920020119US1</p> <p>Art Unit:</p> <p>Examiner:</p> <p>Search string: (4845543 or 5139192 or 5773899 or 5884835 or 6027999 or 6027999 or 6077766 or 6218728 or 6306750).pn</p>							
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4845543	1989-07-04	Okikawa et al			
	2	5139192	1992-08-18	Simmonds			
	3	5773899	1998-06-30	Zambrano			
	4	5884835	1999-06-23	Kajiwara et al			
	5	6027999	2000-02-22	Wong			
	6	6027999	2000-02-22	Wong			
	7	6077766	2000-06-20	Sebesta et al			
	8	6218728	2001-04-17	Kimura			
	9	6306750	2001-10-23	Huang et al			
Signature							
Examiner Name				Date			